

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Original) A chip card, comprising:

 a card body, and
 chip module embedded in said card body and incorporating an integrated circuit, said card body including at least one security feature incorporated in a layer, or applied on a surface, of the card body,
 wherein said card body comprises an additional tamper-detection layer including a conductive pattern forming an electrical loop connected between terminals of the integrated circuit, said conductive pattern having at least one region located beneath or above said security feature, and
 wherein said integrated circuit is adapted to perform an integrity check of said conductive pattern for conditionally performing further operations only in case said integrity is recognized.
2. (Original) The chip card as in claim 1, wherein said conductive pattern has a given impedance or resistance and said integrated circuit is adapted to check whether said impedance or resistance matches a predetermined value stored in a memory of the integrated circuit.
3. (Original) The chip card as in claim 1, wherein said chip card includes contactless communication features and said conductive pattern is part of a tuned circuit co-operating with said integrated circuit for contactless communication.
4. (Original) The chip card as in claim 1, wherein said at least one security feature is a feature from the group including photograph, hologram, multiple laser image, laser engraving, UV/IR-readable pattern and magnetically-readable encoding.
5. (Original) The chip card as in claim 1, wherein said conductive pattern is made from a conductive ink material.

6. (Original) The chip card as in claim 1, wherein said conductive pattern is made from a transparent or near transparent material.
7. (Original) The chip card as in claim 1, wherein said conductive pattern is connected to said terminals of the integrated circuit through permanent bonds.
8. (New) A chip card, comprising:
 - a base layer;
 - an upper layer comprising an integrated circuit, wherein at least one security feature is located on the upper layer; and
 - a security layer interposed between the base layer and the upper layer,
 - wherein the security layer comprises a conductive pattern forming an electrical loop connected between end pads in the security layer,
 - wherein at least one portion of the conductive pattern is located below the at least one security feature, and
 - wherein the conductive pattern is configured to deactivate the integrated circuit when the integrity of the electrical loop is compromised.
9. (New) The chip card of claim 8, wherein the conductive pattern has a given impedance or resistance that is compared with a predetermined value stored in a memory of the integrated circuit for the integrity verification made by the integrated circuit.
10. (New) The chip card of claim 8, wherein the end pads are connected to terminals of the integrated circuit.
11. (New) The chip card as of claim 8, wherein the conductive pattern is made from a conductive ink material.
12. (New) The chip card of claim 11, wherein said conductive pattern is made from a transparent material.

13. (New) The chip card of claim 11, wherein said conductive pattern is made from a near transparent material.